

1/10

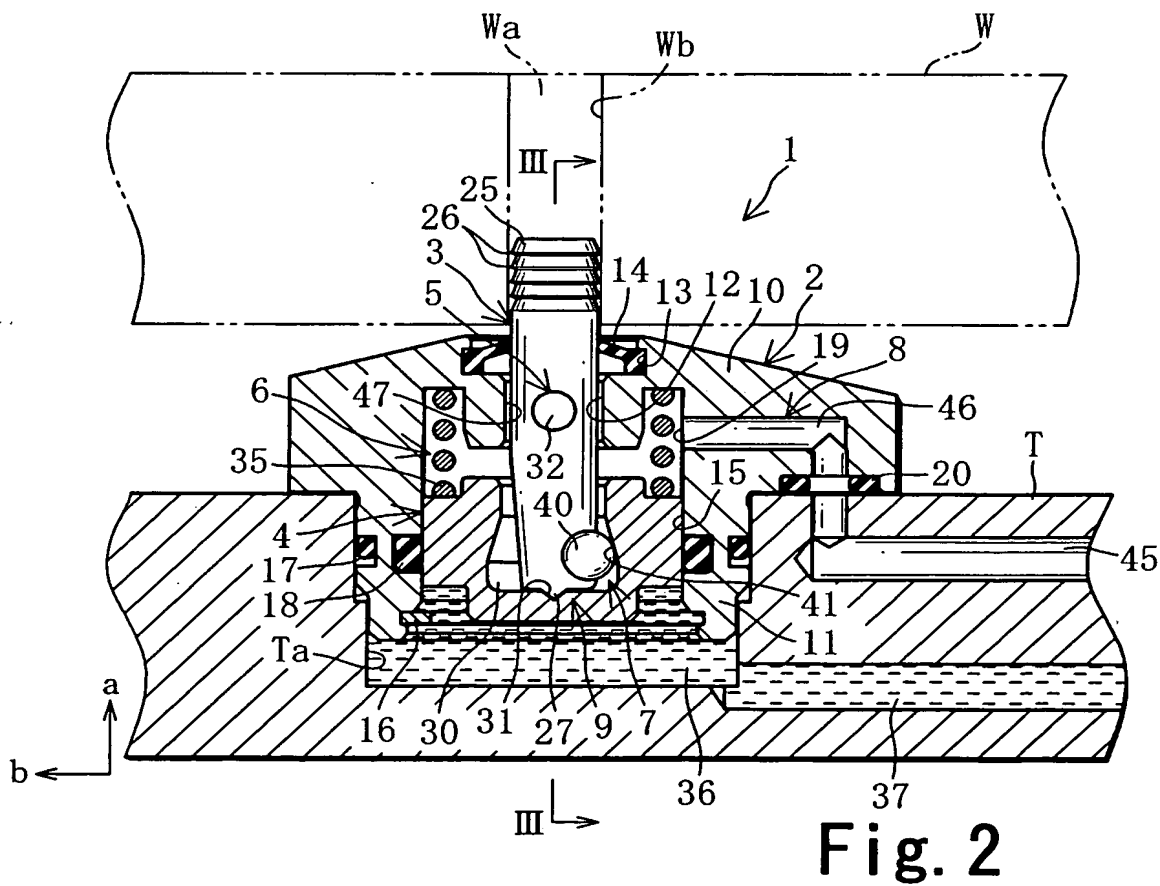
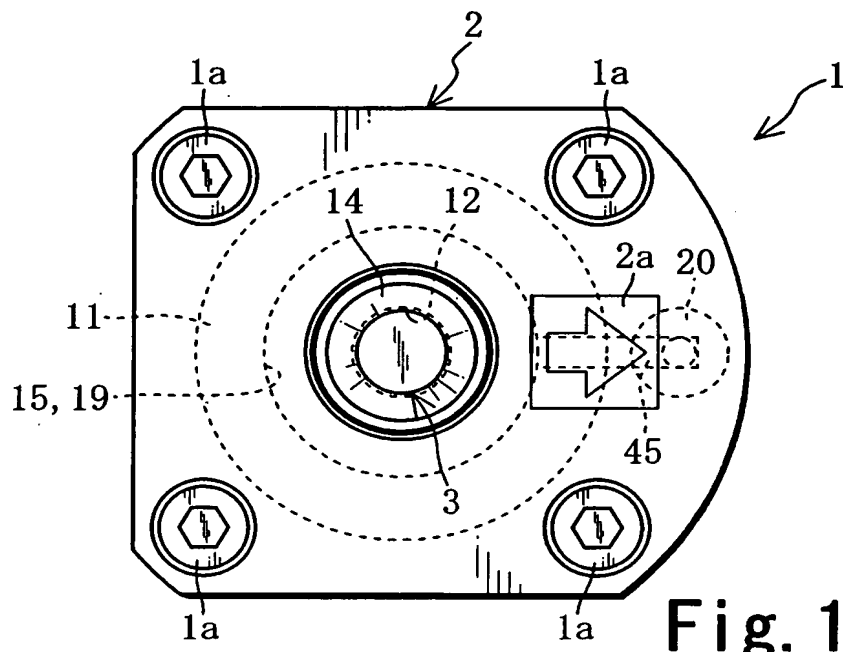
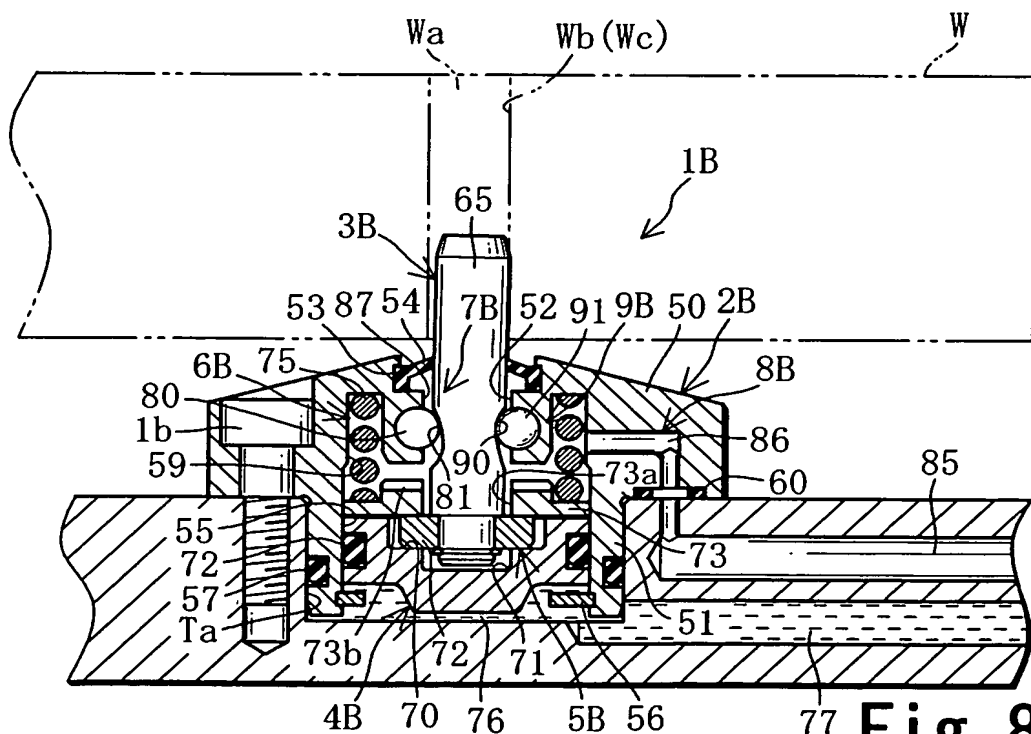
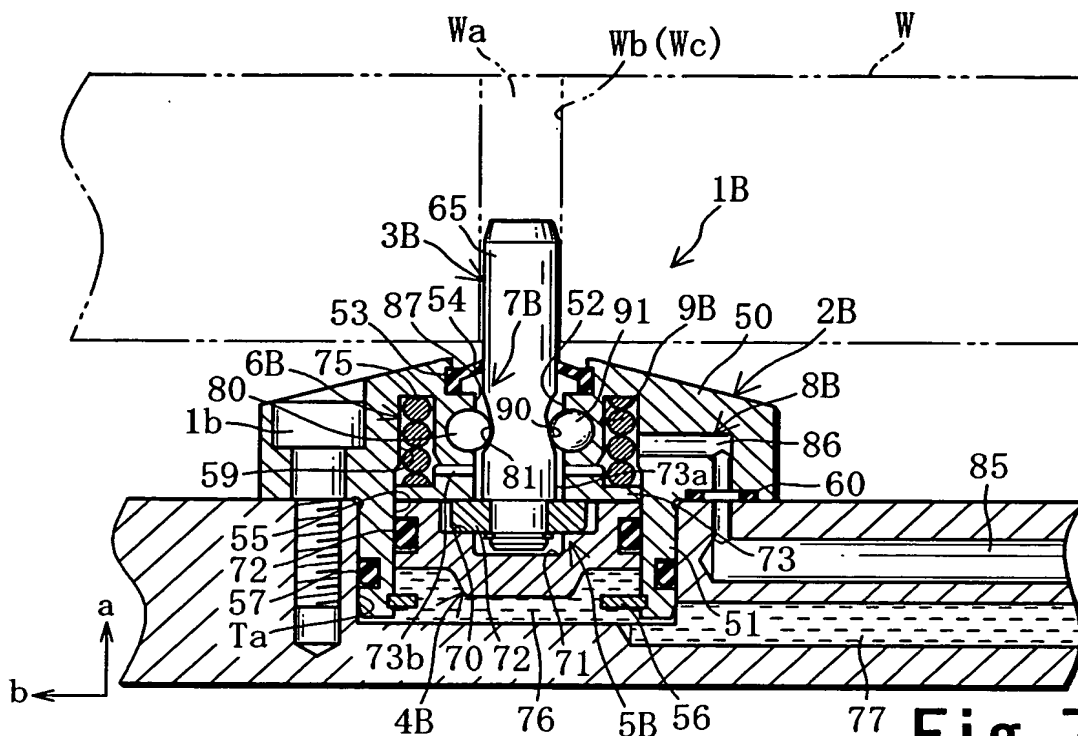


Fig. 1 is a cross-sectional view of a semiconductor device 1. The device is built on a substrate T. A base layer 16 is formed on the substrate. A central vertical structure 12 is surrounded by a ring of contacts 17. A top layer 25 is connected to the central structure via a contact 26. A side contact 32 is also shown. Various other components are labeled with numbers 1 through 47.

**Fig. 4**

Fig. 5

4/10



5/10

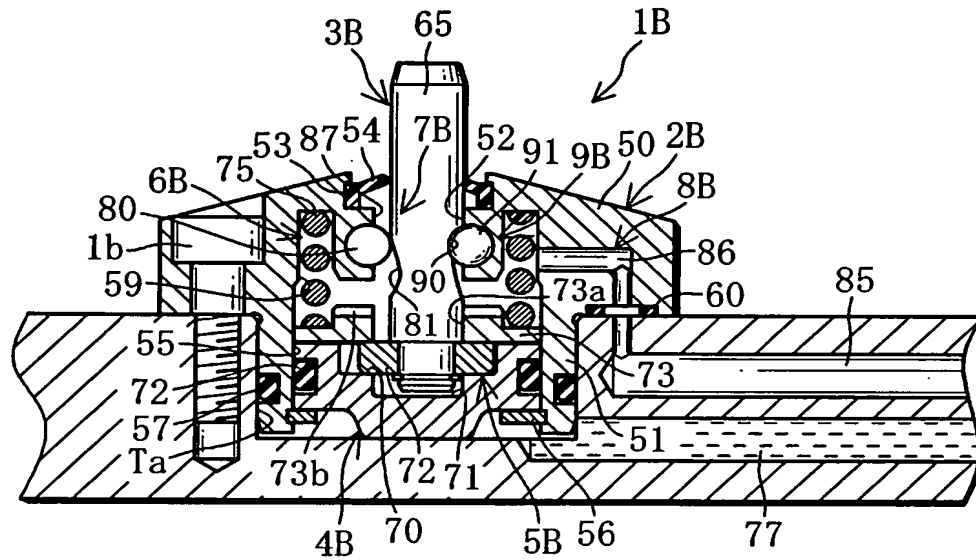


Fig. 9

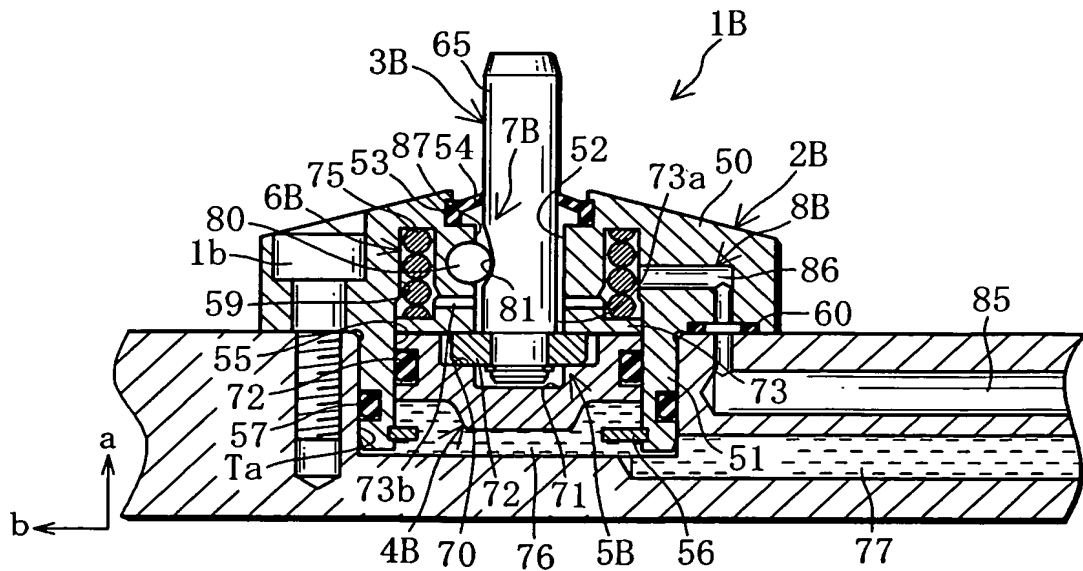


Fig. 10

6/10

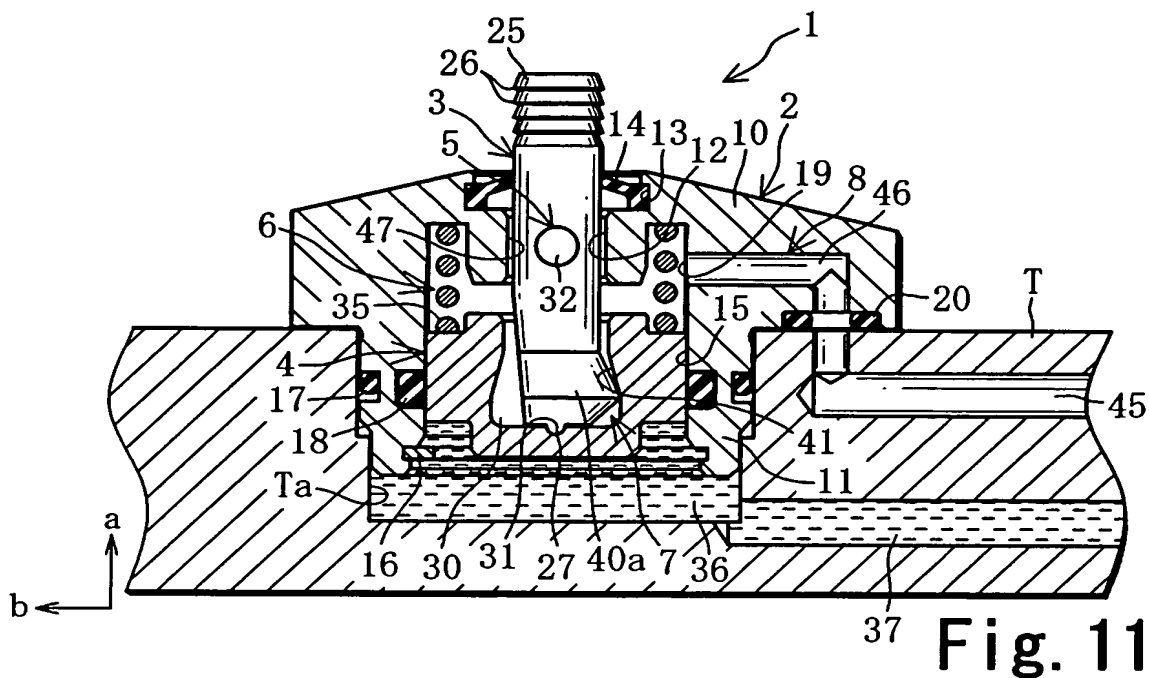


Fig. 11

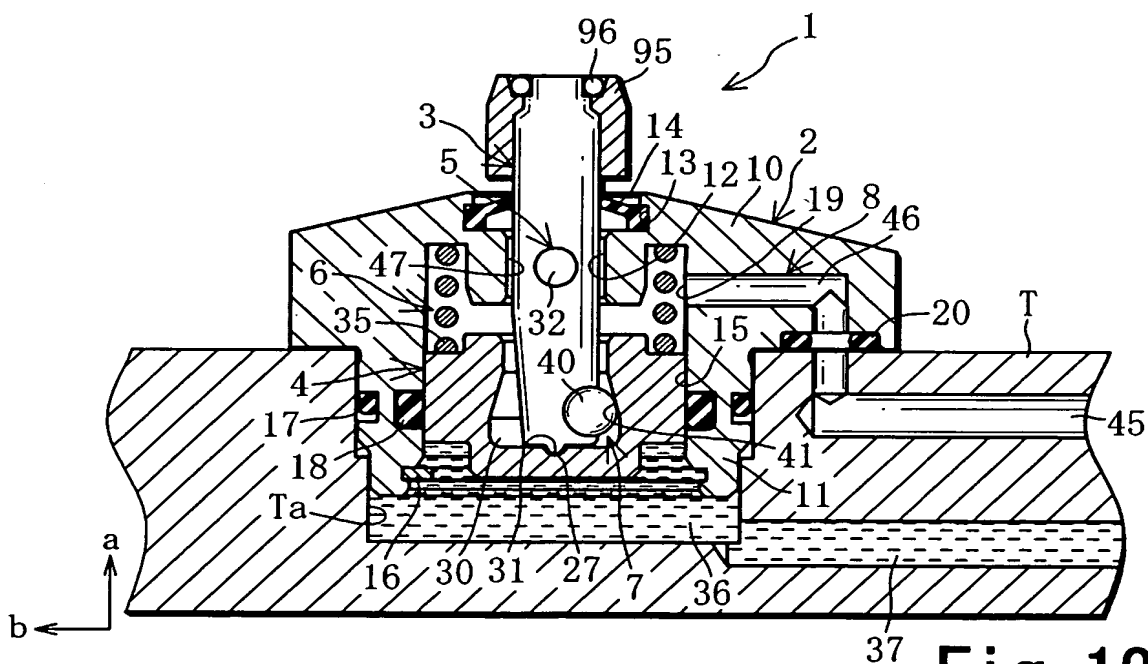
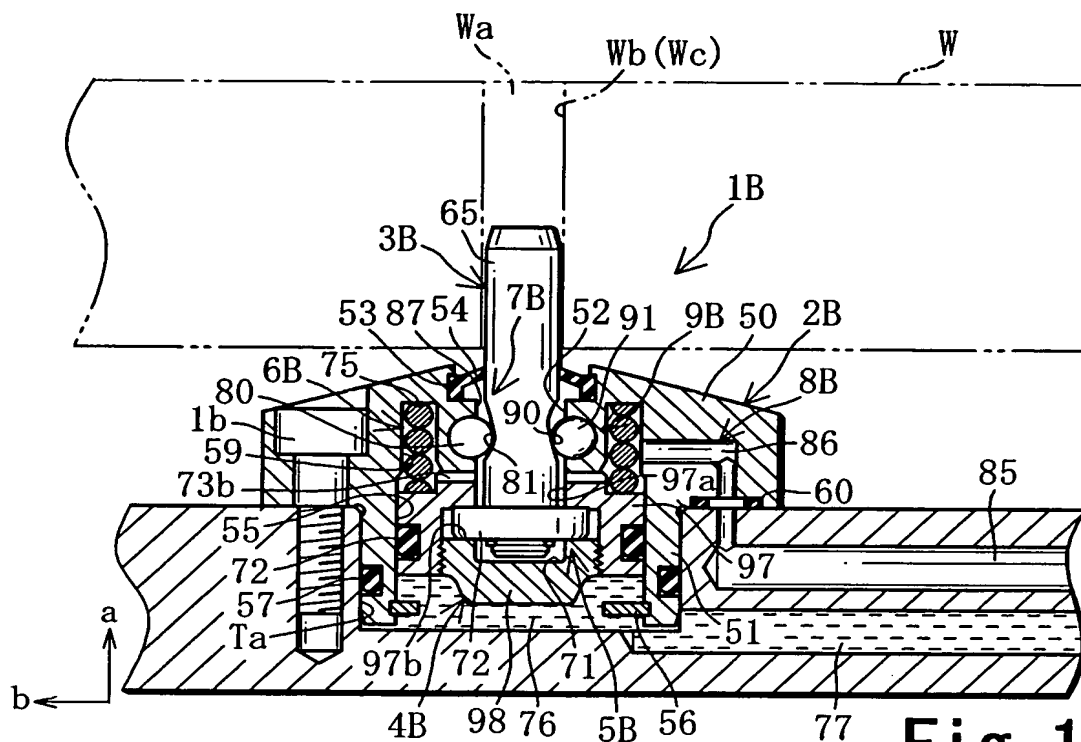


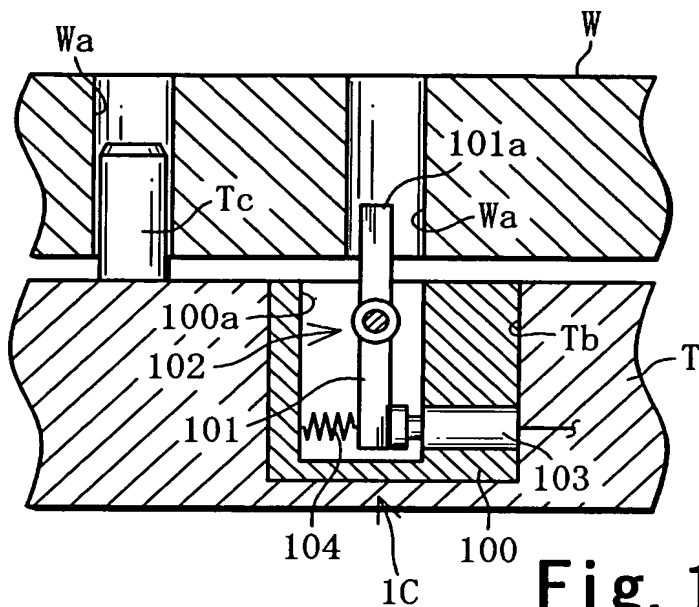
Fig. 12

7 / 10

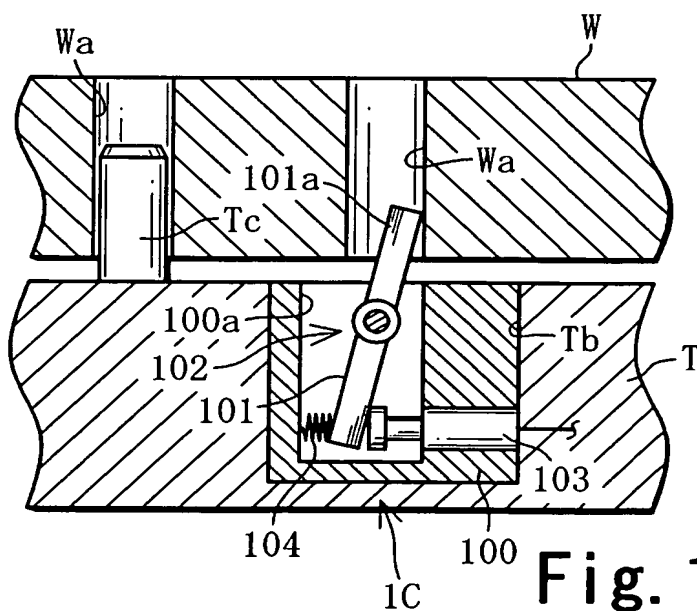


**Fig. 13**

8 / 10



**Fig. 14**



**Fig. 15**



9/10

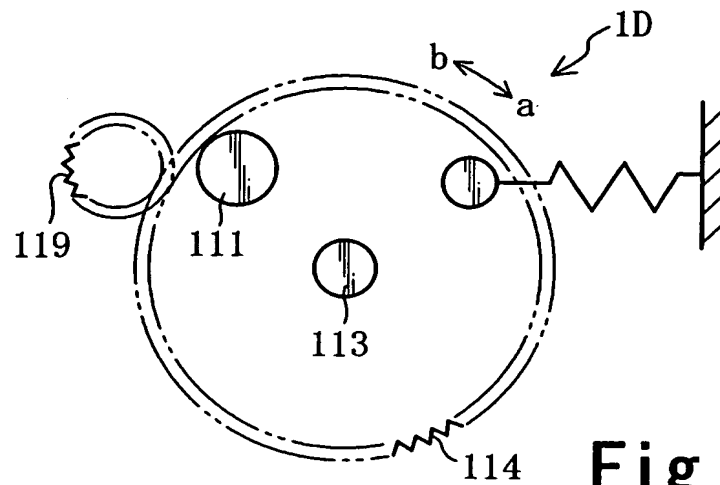


Fig. 16

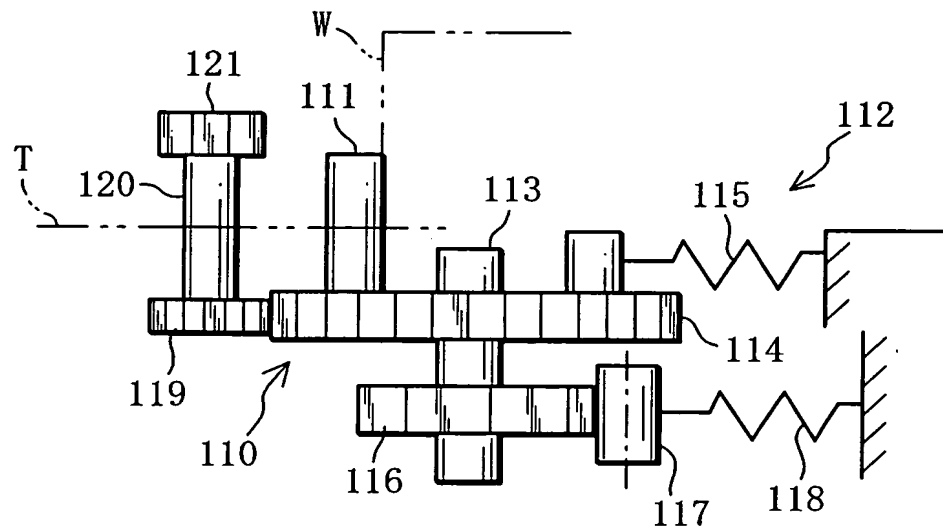


Fig. 17

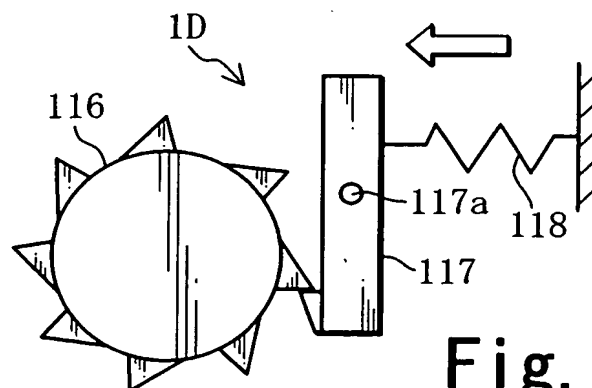


Fig. 18

10/10

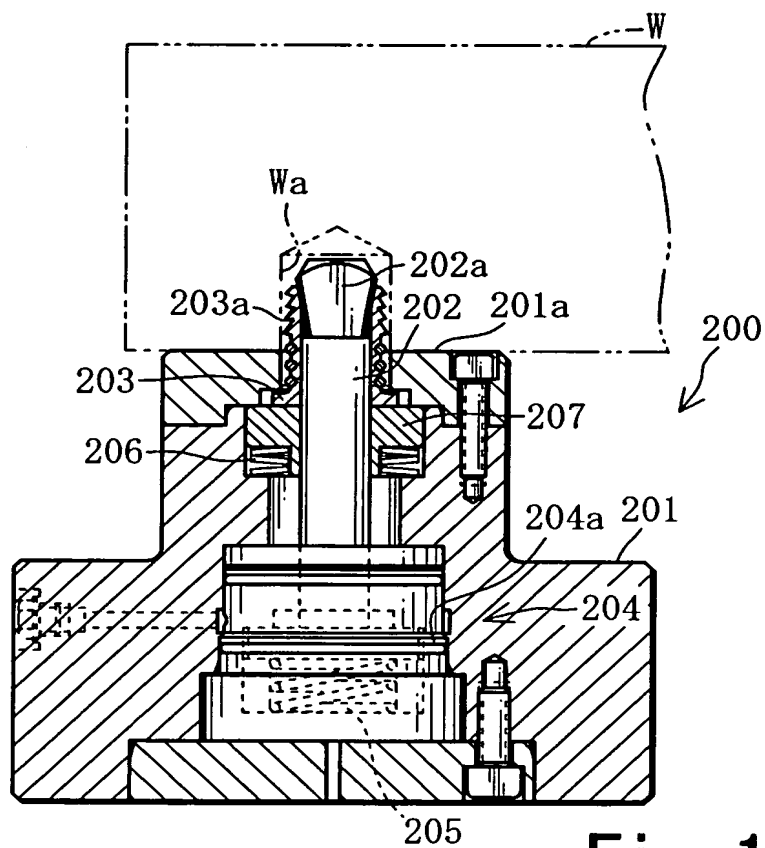


Fig. 19